

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-4 (Canceled).

Claim 5 (Currently Amended): A magnetic memory device ~~according to claim 4,~~  
having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and

a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material,

wherein the lead frame is made of a conductive high-permeability magnetic material,

wherein the high-permeability magnetic material of the lead frame includes a grain-oriented electrical steel, permalloy, a permalloy alloy with elements added, a metal crystal material, a metal amorphous foil, and a ferrite material, and

wherein the metal crystal material includes sendust and Finemet.

Claims 6-8 (Canceled).

Claim 9 (Currently Amended): A magnetic memory device ~~according to claim 7,~~  
having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and

a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material,

wherein the lead frame comprises a frame body of Cu or Fe, whose surface is covered with a high-permeability magnetic material film functioning as the magnetic guide, and wherein the high-permeability magnetic material film is formed of a resin paste containing a high-permeability magnetic powder.

Claim 10 (Original): A magnetic memory device according to claim 9, wherein the high-permeability magnetic powder includes ferrite.

Claims 11-12 (Canceled).

Claim 13 (Currently Amended): A magnetic memory device ~~according to claim 11, having a packaged magnetic memory chip, comprising:~~  
a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material,

wherein the resin is mixed with a high-permeability magnetic particulate, and  
wherein the high-permeability magnetic particulate includes a resin with Mn-Zn  
ferrite and an additive, and a resin with yttrium iron garnet and an additive.

Claims 14-16 (Canceled).

Claim 17 (Currently Amended): A magnetic memory device ~~according to claim 15,~~  
having a packaged magnetic memory chip, comprising:  
a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural  
member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory  
chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory  
chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin  
forms the magnetic guide containing a high-permeability magnetic material,

wherein a plurality of the magnetic memory chips are stacked in a multi-layer form  
and sealed by a resin, and

wherein at least one of the die bonding agents which bond the adjacent magnetic  
memory chips and the die which bonds agent bonding the lowermost magnetic memory chip  
and the lead frame contains a high-permeability magnetic powder.

Claim 18 (Currently Amended): A magnetic memory device ~~according to claim 15,~~  
having a packaged magnetic memory chip, comprising:  
a package structure including a magnetic memory chip; and

a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material,

wherein a plurality of the magnetic memory chips are stacked in a multi-layer form and sealed by a resin, and

wherein at least one of the die bonding agents which bond the adjacent magnetic memory chips and the die bonding agent which bonds the lowermost magnetic memory chip and the lead frame comprises a sheet member having a foil member of a high-permeability magnetic material held between two adhesive resin sheets.

Claims 19-20 (Canceled).

Claim 21 (Currently Amended): A magnetic memory device ~~according to claim 19,~~ having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a lead frame on which the magnetic memory chip is bonded by a die bonding agent and a resin which seals the bonded magnetic memory chip, and wherein at least one of the lead frame, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material,

wherein a plurality of the magnetic memory chips are stacked in a multi-layer form and sealed by a resin,

wherein at least one of an upper portion of the resin which covers an upper surface of the stacked magnetic memory chip and a lower portion of the resin which covers a lower surface of the stacked magnetic memory chip is mixed with a high-permeability magnetic particulate, and

wherein the high-permeability magnetic particulate includes a resin with Mn-Zn ferrite and an additive, and a resin with yttrium iron garnet and an additive.

Claims 22-23 (Canceled).

Claim 24 (Currently Amended): A magnetic memory device according to claim 23, having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a heat sink having a central portion on which the magnetic memory chip is bonded by a die bonding agent, a wiring board bonded on a peripheral portion of the heat sink, to which terminals of the magnetic memory chip are lead-out, and a resin which seals the magnetic memory chip, and wherein at least one of the heat sink, the die bonding agent and the sealing resin forms the magnetic guide containing a high-permeability magnetic material, and

wherein the heat sink comprises a heat sink body of Cu or Al, whose surface is covered with a high-permeability magnetic material film functioning as the magnetic guide.

Claim 25 (Original): A magnetic memory device according to claim 24, wherein the high-permeability magnetic material includes ferrite of spinel type and ferrite of garnet type.

Claim 26 (Original): A magnetic memory device according to claim 24, wherein the high-permeability magnetic material includes a resin with Mn-Zn ferrite and an additive, and a resin with yttrium iron garnet and an additive.

Claims 27-28 (Canceled).

Claim 29 (Currently Amended): A magnetic memory device ~~according to claim 27,~~  
having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural  
member of the package structure,

wherein the package structure includes a base board in which leading-out wires are  
formed and on which the magnetic memory chip is bonded by a die bonding agent, and a  
resin which seals the magnetic memory chip, and wherein at least one of the base board, the  
die bonding agent and the sealing resin forms a magnetic guide containing a high-  
permeability magnetic material, and

wherein the base board is made of a high-permeability magnetic material and functions as the magnetic guide.

Claims 30-31 (Canceled).

Claim 32 (Currently Amended): A magnetic memory device according to claim 30,  
having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and

a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a base board in which leading-out wires are formed and on which the magnetic memory chip is bonded by a die bonding agent, and a resin which seals the magnetic memory chip, and wherein at least one of the base board, the die bonding agent and the sealing resin forms a magnetic guide containing a high-permeability magnetic material,

wherein the base board is made of a material containing no magnetic particulates, and the resin is mixed with high-permeability magnetic particulates and functions as the magnetic guide, and

wherein the high-permeability magnetic material includes a resin with Mn-Zn ferrite and an additive, and a resin with yttrium iron garnet and an additive.

Claim 33 (Canceled).

Claim 34 (Currently Amended): A magnetic memory device according to claim 33,  
having a packaged magnetic memory chip, comprising:

a package structure including a magnetic memory chip; and

a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a base board in which leading-out wires are formed and on a chip mounting depression of which the magnetic memory chip is bonded by

a die bonding agent, and a resin which seals the magnetic memory chip, and wherein at least one of the base board, the die bonding agent and the sealing resin forms a magnetic guide containing a high-permeability magnetic material, and

wherein the base board is made of a high-permeability magnetic material and functions as the magnetic guide.

Claims 35-36 (Canceled).

Claim 37 (Currently Amended): A magnetic memory device according to claim 35, having a packaged magnetic memory chip, comprising:  
a package structure including a magnetic memory chip; and  
a magnetic guide of a high-permeability magnetic material, forming a structural member of the package structure,

wherein the package structure includes a base board in which leading-out wires are formed and on a chip mounting depression of which the magnetic memory chip is bonded by a die bonding agent, and a resin which seals the magnetic memory chip, and wherein at least one of the base board, the die bonding agent and the sealing resin forms a magnetic guide containing a high-permeability magnetic material,

wherein the base board is made of a material containing no magnetic particulates, and the resin is mixed with a high-permeability magnetic material and functions as the magnetic guide, and

wherein the high-permeability magnetic material includes a resin with Mn-Zn ferrite and an additive, and a resin with yttrium iron garnet and an additive.